

### **40V N-Channel Enhancement Mode MOSFET**

#### Description

The SX3N04AI uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### **General Features**

V<sub>DS</sub> = 40V I<sub>D</sub> =3A

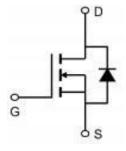
 $R_{DS(ON)} < 40 m\Omega$  @  $V_{GS}=10V$ 

#### **Application**

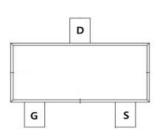
Wireless charging

Boost driver

LED







#### Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

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Symbol	Parameter	Rating	Units	
VDS	Drain-Source Voltage	40	V	
Vgs	Gate-Source Voltage	±20	V	
lo@Ta=25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	3	А	
lo@Ta=70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	2.9	А	
Ірм	Pulsed Drain Current <sup>2</sup>	15	А	
EAS	Single Pulse Avalanche Energy³	16.2	mJ	
P <b>o@T</b> a=25°C	Total Power Dissipation <sup>4</sup>	1.67	W	
Тѕтс	Storage Temperature Range	-55 to 150	$^{\circ}$	
TJ	Operating Junction Temperature Range	-55 to 150	$^{\circ}$	
Reja	Thermal Resistance Junction-Ambient <sup>1</sup>	125	°C/W	
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	30	°C/W	

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### N-Channel Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	Vgs=0V , Ip=250uA	40	44		V
∆BVDSS/∆TJ	BVDSS Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =1mA		0.032		V/°C
DDC(ON)	Otatia Dunin Causas On Basistanas?	Vgs=10V , Ip=4A		28	40	mΩ
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	Vgs=4.5V , In=3A		35	50	
VGS(th)	Gate Threshold Voltage	\/ \/   050A	1.0	1.5	2.5	V
$\triangle V$ GS(th)	V <sub>GS(th)</sub> Temperature Coefficient	Vgs=Vds , Id =250uA		-4.5		mV/℃
IDSS	Duein Course Leekens Cument	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
וחפפ	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	
IGSS	Gate-Source Leakage Current	Vgs=±20V , Vps=0V			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =4A		8		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.4	4.8	Ω
Qg	Total Gate Charge (4.5V)	Vps=15V , Vgs=4.5V , Ip=3A		5		nC
Qgs	Gate-Source Charge			1.54		
Qgd	Gate-Drain Charge			1.84		
Td(on)	Turn-On Delay Time			7.8		ns
Tr	Rise Time	$V_{DD}$ =15 $V$ , $V_{GS}$ =10 $V$ , $R_{G}$ =3.3 $\Omega$		2.1		
Td(off)	Turn-Off Delay Time			29		
Tf	Fall Time	lo=1A		2.1		
Ciss	Input Capacitance			452		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		51		pF
Crss	Reverse Transfer Capacitance			38		
IS	Continuous Source Current <sup>1,4</sup>	V V 0V 5			4.5	Α
ISM	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			14	Α
VSD	Diode Forward Voltage <sup>2</sup>	Vgs=0V,Is=1A,Tյ=25℃			1.2	V

#### Note:

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- $2_{\times}$  The data tested by pulsed , pulse width  $\leq 300 us$  , duty cycle  $\leq 2\%$
- 3. The power dissipation is limited by 150  $\!\!\!\!^{\circ}\!\!\!\!^{\circ}$  junction temperature
- $4_{\tiny N}$  The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

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## **Typical Characteristics**

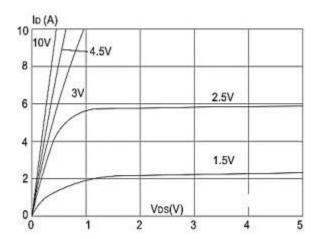


Figure1: Output Characteristics

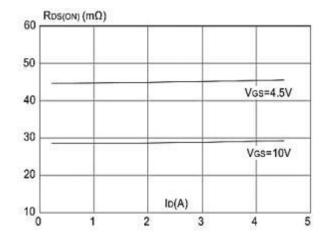
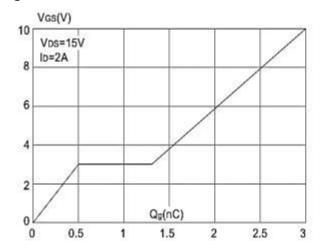
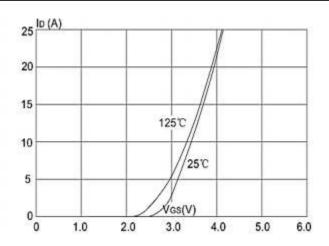


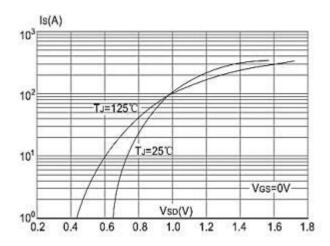
Figure 3:On-resistance vs. Drain Current



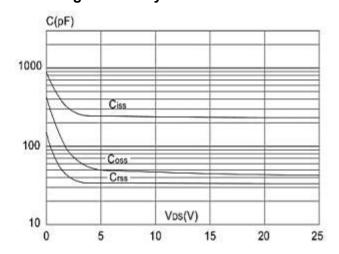
**Figure 5: Gate Charge Characteristics** 



**Figure 2: Typical Transfer Characteristics** 



**Figure 4: Body Diode Characteristics** 



**Figure 6: Capacitance Characteristics** 





### **Typical Characteristics**

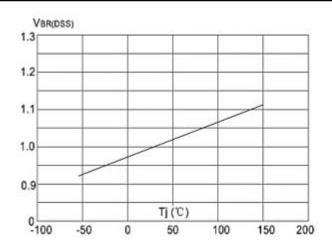


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

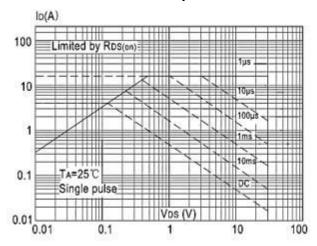


Figure 9: Maximum Safe Operating Area vs. Case Temperature

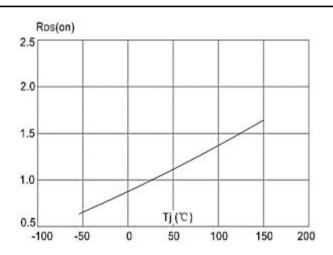
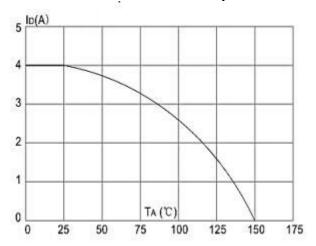


Figure 8: Normalized on Resistance vs Junction Temperature



**Figure 10: Maximum Continuous Drain Current** 

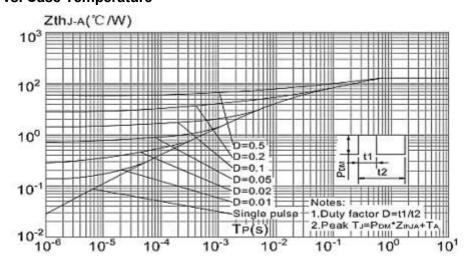


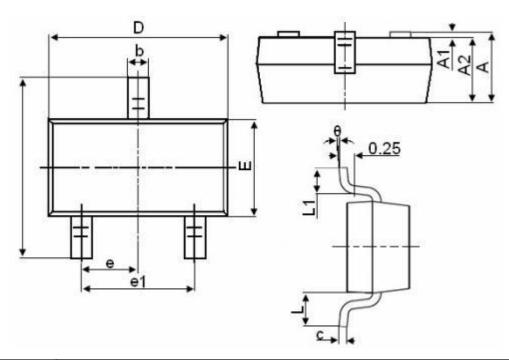
Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

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# Package Mechanical Data-SOT23-XC-Single



Cymahal	Dimensions in Millimeters		
Symbol	MIN.	MAX.	
Α	0.900	1.150	
A1	0.000	0.100	
A2	0.900	1.050	
b	0.300	0.500	
С	0.080	0.150	
D	2.800	3.000	
Е	1.200	1.400	
E1	2.250	2.550	
е	0.950TYP		
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.500	
θ	0°	8°	

**Package Marking and Ordering Information** 

i	. dokago marking and ordoring information					
	Product ID	Pack	Marking	Qty(PCS)		
	TAPING	SOT23		3000		

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